



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**PATENT**

#5/A 2/23/02  
D

**In re Application of:**

Cobbley et al.

**Serial No.:** 09/639,486

**Filed:** August 14, 2000

**For:** METHOD OF ATTACHING SOLDER BALLS TO BGA PACKAGE UTILIZING A TOOL TO PICK AND DIP THE SOLDER BALL IN FLUX

**Examiner:** Z. Pittman

**Group Art Unit:** 1725

**Attorney Docket No.:** 3636.1US (97-1349.1)

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

January 30, 2002  
Date of Deposit

Signature of registered practitioner or other person having reasonable basis to expect mailing to occur on date of deposit shown pursuant to 37 C.F.R. § 1.8(a)(1)(ii)

Deidra Pfeil  
Typed/printed name of person whose signature is contained above

**AMENDMENT**

Box NON-FEE AMENDMENT  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

This amendment is in response to the Office Action of October 31, 2001 whose initial period of response is set to expire on January 31, 2002.

RECEIVED  
FEB 20 2002  
TC 1700  
COPY OF PAPERS  
SUBMITTED TO  
OFFICE OF PATENTS

A